

Data sheet **2.5V Power clamp**

UMC 65nm

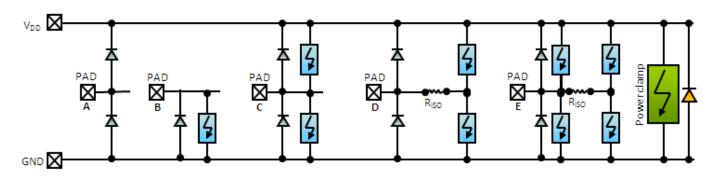
Sofics has verified its TakeCharge ESD protection clamps on technology nodes between 0.25um CMOS down to 28nm across various fabs and foundries. The ESD clamps are silicon and product proven in more than 1500 mass produced IC-products. The cells provide competitive advantage through improved yield, reduced silicon footprint and enable advanced multimedia and wireless interfaces like HDMI, USB 3.0, SATA, WIFI, GPS and Bluetooth.

The ESD clamp described in this document protects 2.5V domains in UMC 65nm CMOS technology.

UMC 65nm 2.5V Power clamp

Clamp type and usage

The Sofics ESD cells cover all types of protection concepts and approaches as detailed in the figure below. The ESD clamp cell described in this document is a type power clamp.



UMC 65nm	2.5V	Comments
Core Protection	YES	
Input Protection		
Output Protection		
I/O Protection		
Over Voltage Tolerant I/O (OVT)		
Under Voltage Tolerant I/O (UVT)		
Inter Domain Protection		

Stress cases covered

PAD to VSS		VSS to PAD	
VDD to PAD		PAD to VDD	
VDD to VSS	Power clamp	VSS to VDD	Reverse diode

Connections in the cell

• Vdd, Vss

Features

- Efficient ESD protection
 - > 7.8 kV Human Body Model (HBM)
 - > 470 V Machine Model (MM)
- Leakage <10nA measured at 2.75V
- Silicon footprint <3800um²

Sofics Proprietary – ©2012 Page 2

Maximum ratings

Rating	Symbol	Value		Unit
		Min	Max	
Supply Voltage Range (DC)	V_{DD}	-0.3	2.75	V
Input/Output Voltage Range (DC)	V _{IO}	-0.3	2.75	V
Operating Temperature	T _{op}	-25	125	°C
Burn-in Voltage (DC @ 125°C)		3.75		V



Stresses exceeding these maximum ratings may damage the device. Functional operation above the recommended operating conditions is not implied. Extended exposure to stresses above the recommended operating conditions may affect device reliability.

The provided golden cell is designed for these maximum ratings/specifications. If the desired specification level differs, the golden cell has to be scaled up or down by using the Sofics implementation/scaling guidelines to remain a robust and effective ESD protection for the different specifications.

Electrical Characteristics

T_{amb} = 25°C unless stated otherwise

Parameter	Symbol	Тур.	Unit
Tripper Valtage	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	C 1	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
Trigger Voltage	V _{t1}	6.1	V
Holding Voltage	V_h	4	V
Leakage current @ T _{amb} = 25 °C	I _{leak}	<10	nA
Leakage current @ T _{amb} = 120 °C	I _{leak}		
Total Capacitance Load, 0V bias	C _L		fF
Required (for ESD) resistance	R _{iso}	0	Ohm
between bondpad and functional circuit			
HBM – Human Body Model		7.8	kV
MM – Machine Model		470	V

Process, Area and integration

• Process: UMC 65nm

Used Metals: metals – customization service available

Special layers needed: N/A

• Area: 3799.18 um² (77 um x 49.34 um)

Sofics Proprietary – ©2012 Page 3

Data sheet: UMC 65nm 2.5V Power clamp DS-UM65-PC2V5

About Sofics

Sofics (www.sofics.com) is the world leader in on-chip ESD protection. Its patented technology is proven in more than a thousand IC designs across all major foundries and process nodes. IC companies of all sizes rely on Sofics for off-the-shelf or custom-crafted solutions to protect overvoltage I/Os, other non-standard I/Os, and high-voltage ICs, including those that require system-level protection on the chip. Sofics technology produces smaller I/Os than any generic ESD configuration. It also permits twice the IC performance in high-frequency and high-speed applications. Sofics ESD solutions and service begin where the foundry design manual ends.



ESD SOLUTIONS AT YOUR FINGERTIPS

Our service and support

Our business models include

- Single-use, multi-use or royalty bearing license for ESD clamps
- Services to customize ESD protection
 - o Enable unique requirements for Latch-up, ESD, EOS
 - o Layout, metallization and aspect ratio customization
 - o Area, capacitance, leakage optimization
- Transfer of individual clamps to another target technology
- Develop custom ESD clamps for foundry or proprietary process
- Debugging and correcting an existing IC or IO
- ESD testing and analysis

Notes

As is the case with many published ESD design solutions, the techniques and protection solutions described in this data sheet are protected by patents and patents pending and cannot be copied freely. PowerQubic, TakeCharge, and Sofics are trademarks of Sofics BVBA.

Version

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Sofics Proprietary – ©2012 Page 4